



FORM HDP-1449 (Based on Form PTO-1449)

**PATENT AND TRADEMARK OFFICE
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Sheet 1 of 1

ATTORNEY DOCKET NO.

SERIAL NO.

7784-000553/CPA

10/674,615

APPLICANT

Terry L. Schneider

FILING DATE

GROUP

September 30, 2003

1772

U.S. PATENT DOCUMENTS

Ref. Desig.	Examiner's Initials	Document Number	Date	Name	Class/ Subclass	(If appropriate) Filing Date
1.	<i>MD</i>	5,614,305	03/1997	Paine et al		

FOREIGN PATENT DOCUMENTS

Ref. Desig.	Examiner's Initials	Document Number	Date	Country	Class/ Subclass	Translation Yes	No
1.							

OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)

Ref. Desig.	Examiner's Initials	
1.	<i>MD</i>	Ni-Ti SMA-Reinforced Al Composites by G.A. Porter, P.K. Liaw, T.N. Tiegs and K.H. Wu, October, 2000
2.	<i>MD</i>	"Preparation of a smart composite material with TiNiCu shape memory particulates in an aluminum matrix" by Z.G. Wei, C.Y. Tang, W.B. Lee, L.S. Cui and D.Z. Yang; October 1997
3.	<i>MD</i>	"Increased Impact Damage Resistance of Shape Memory Alloy Composites" by Kelly A. Tsoi, Rudy Stalmans, Martine Wevers, Jan Schrooten and Yiu-Wing Mai; date unknown
4.	<i>MD</i>	"Fracture toughening mechanism of shape memory alloys due to martensite transformation" by Sung Yi and Shan Gao; date unknown
5.	<i>MD</i>	"On the Interaction Between Transformation Toughening and Crack Bridging by Ductile Layers in Hybrid Composites" by M. Li, N. Katsube and W.O. Soboybio, Journal of Composite Materials, Vol. 35, No. 12/2001
6.	<i>MD</i>	"The Evolution of an Aerospace Material: Influence of Design, Manufacturing, and In-Service Performance" by Alan G. Miller and Donald T. Lovell and James C. Seferis; Composite Structures 0263-8223/93/S06.00; 1993 Elsevier Science Publishers Ltd., England

Examiner:

MD

Date Considered:

6/04

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